

IN THE CLAIMS

1. (Original) A semiconductor device, comprising:

- an integrated circuit chip;
- a base to which said integrated circuit chip is mounted and connected;
- a plurality of terminals disposed on said base for connection of said integrated circuit chip to the outside;
- a plurality of metal bumps one formed on each of said plurality of terminals; and
- a supporting frame for fixedly supporting said integrated circuit chip or said base,

wherein said base includes a circuit board or a circuit film having a circuit pattern formed on an insulating base.

Claims 2-34 (Canceled)